

SOT537-1

plastic low profile fine-pitch ball grid array package; 114 balls; body 16 x 5.5 x 1.05 mm

8 February 2016

Package information

1. Package summary

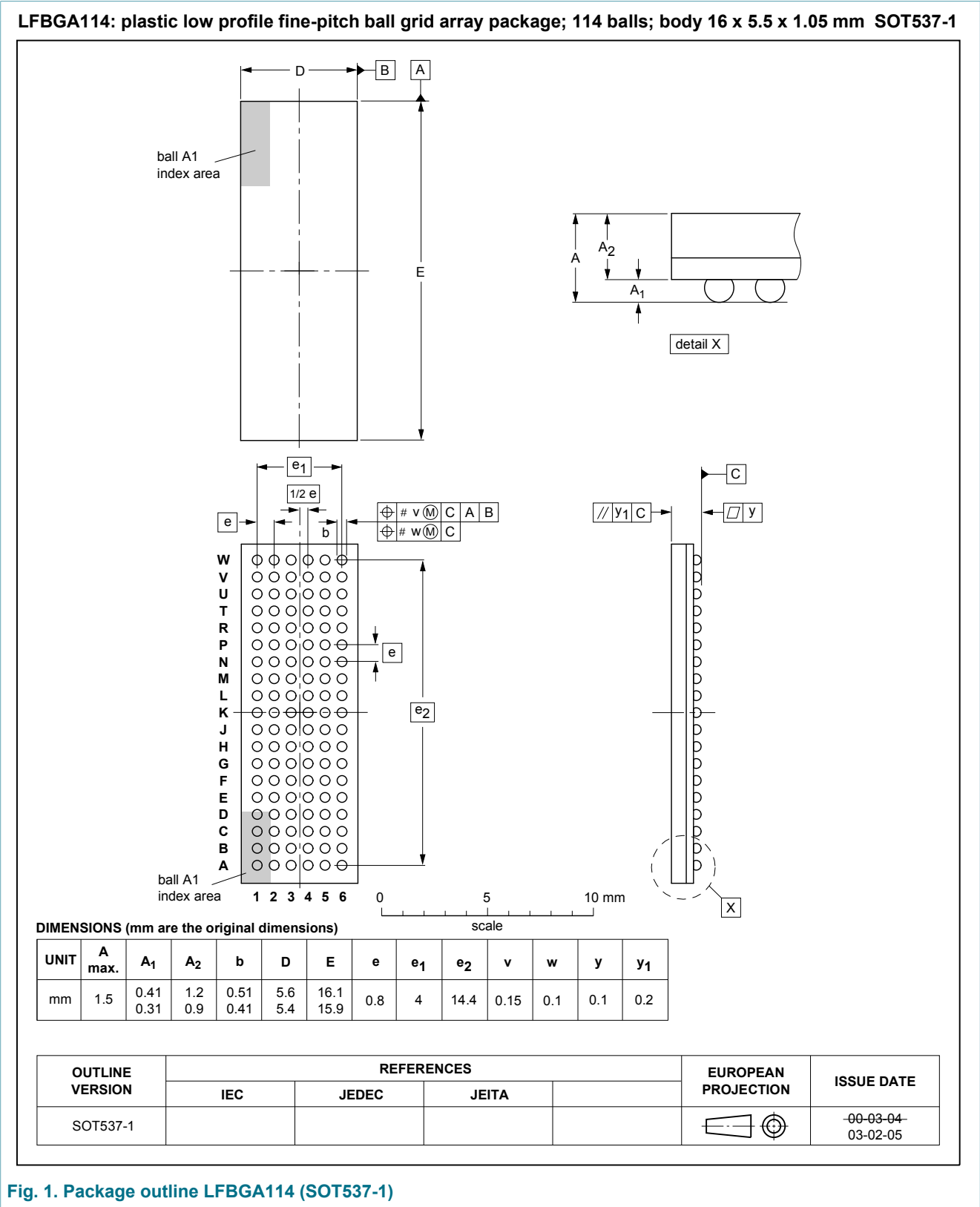
Terminal position code	B (bottom)
Package type descriptive code	LFBGA114
Package type industry code	LFBGA114
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	5-2-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		5.4	-	5.5	5.6	mm
E	package width		15.9	-	16	16.1	mm
A	seated height		[tbd]	-	1.5	1.5	mm
A ₂	package height		0.9	-	1.05	1.2	mm
n ₂	actual quantity of termination		-	-	114	-	



2. Package outline



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3. Soldering

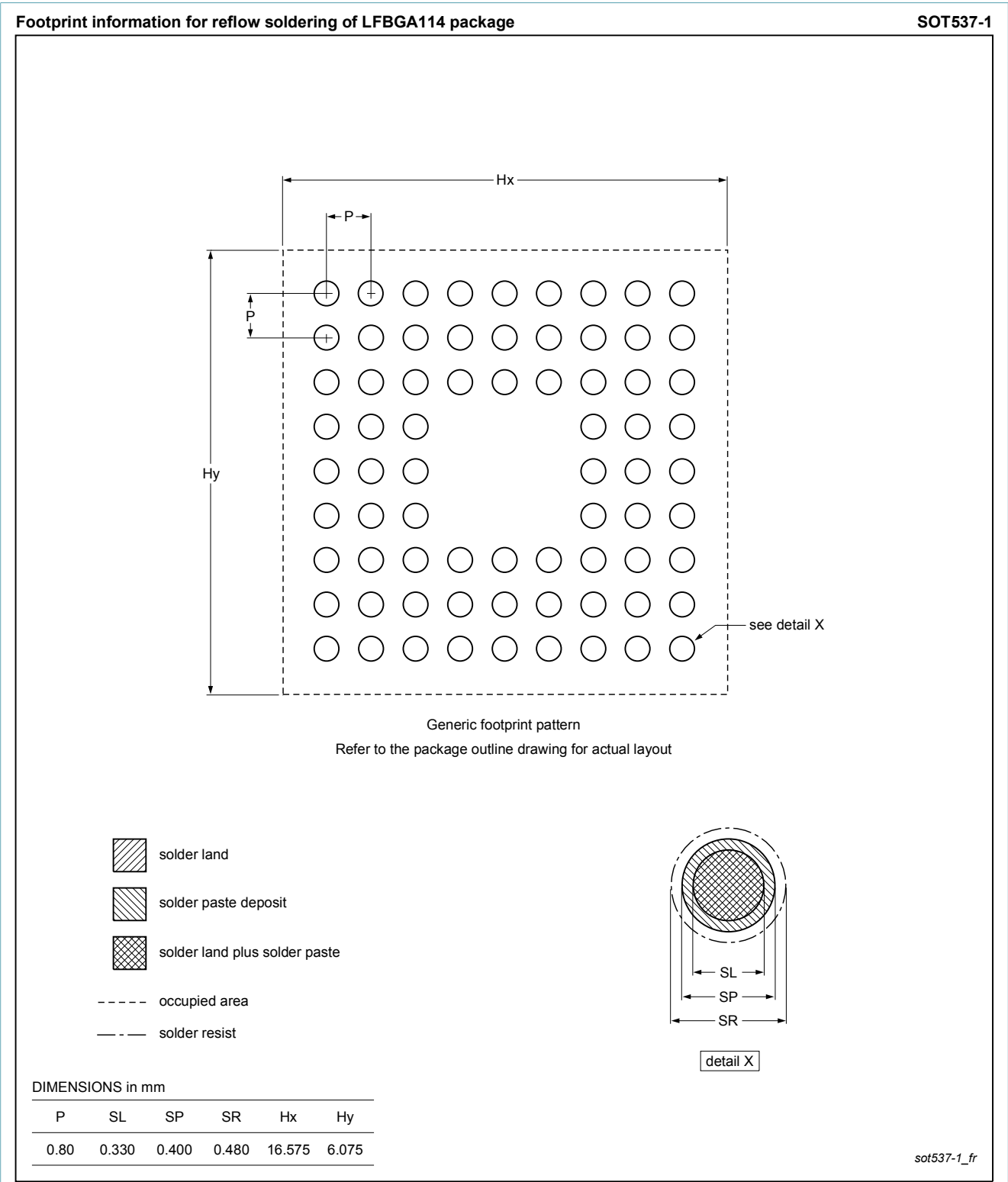


Fig. 2. Reflow soldering footprint for LFBGA114 (SOT537-1)

4. Legal information

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